

| V _{DSS} | 30V |
|----------------------------|-------|
| R _{DS(on)} (Max.) | 5.0mΩ |
| I _D | 14A |
| P _D | 3W |

Features

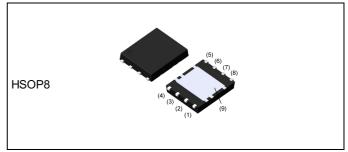
- 1) Low on resistance
- 2) Pb-free plating; RoHS compliant
- 3) Halogen Free

Application

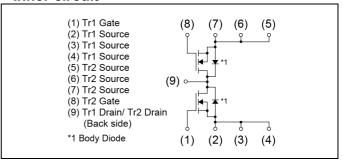
Load Switch

LiB charging and discharging switch

Outline



●Inner circuit



Packaging specifications

| or dokaging opcomodions | | | | | |
|-------------------------|-----------------|------------------|--|--|--|
| | Packing | Embossed Tape | | | |
| | Reel size (mm) | 330 | | | |
| Туре | Tape width (mm) | 12 | | | |
| | Quantity (pcs) | 2500 | | | |
| | Taping code | ТВ | | | |
| | Marking | HP8KA1 | | | |

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified) < Tr1 and Tr2>

| | • • | | |
|--|--------------------|-------------|------|
| Parameter | Symbol | Value | Unit |
| Drain - Source voltage | V_{DSS} | 30 | V |
| Continuous drain current | I _D *1 | 14 | Α |
| Pulsed drain current | I _{DP} *2 | 28 | Α |
| Gate - Source voltage | V_{GSS} | ±20 | V |
| Power dissipation | P _D *3 | 3 | W |
| Junction temperature | T _j | 150 | °C |
| Operating junction and storage temperature range | T _{stg} | -55 to +150 | °C |

●Thermal resistance

| Parameter | C: made al | Values | | | l leit |
|--|----------------------|--------|------|------|--------|
| Parameter | Symbol | Min. | Тур. | Max. | Unit |
| Thermal resistance, junction - ambient | R _{thJA} *3 | - | - | 41 | °C/W |

ullet Electrical characteristics (T_a = 25°C) <It is the same characteristics for the Tr1 and Tr2>

| Davamatav | Cymahal | Conditions | Values | | | Unit |
|--|---|--|--------|------|------|-------|
| Parameter | Symbol | Cymbol | | Тур. | Max. | Offic |
| Drain - Source breakdown voltage | V _{(BR)DSS} | V _{GS} = 0V, I _D = 1mA | 30 | - | - | V |
| Breakdown voltage temperature coefficient | $\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$ | I _D = 1mA referenced to | - | 21 | - | mV/°C |
| Zero gate voltage drain current | I _{DSS} | V _{DS} = 24V, V _{GS} = 0V | 1 | - | 1 | μA |
| Gate - Source leakage current | I _{GSS} | $V_{GS} = \pm 20V, V_{DS} = 0V$ | - | - | ±100 | nA |
| Gate threshold voltage | V _{GS(th)} | V _{DS} = 10V, I _D = 10mA | 1.0 | - | 2.5 | V |
| Gate threshold voltage temperature coefficient | $\frac{\DeltaV_{GS(th)}}{\DeltaT_j}$ | I _D = 1mA referenced to | - | -3 | - | mV/°C |
| Static drain - source | D *4 | V _{GS} = 10V, I _D = 14A | - | 3.5 | 5.0 | |
| on - state resistance | R _{DS(on)} *4 | V _{GS} = 4.5V, I _D = 14A | - | 5.0 | 7.0 | mΩ |
| Forward Transfer Admittance | Y _{fs} *4 | V _{DS} = 5V, I _D = 14A | 14 | - | - | S |

^{*1} Limited only by maximum temperature allowed.

^{*2} Pw ≤ 10µs, Duty cycle ≤ 1%

^{*3} Mounted on a Cu board (40×40×0.8mm)

^{*4} Pulsed

• Electrical characteristics ($T_a = 25$ °C) < Tr1 and Tr2>

| Daramatar | Cymbol | Conditions | Values | | | Unit |
|------------------------------|------------------------|---|--------|------|------|-------|
| Parameter | ter Symbol Conditions | | Min. | Тур. | Max. | Uniit |
| Input capacitance | C _{iss} | V _{GS} = 0V | 1 | 2550 | 1 | |
| Output capacitance | C _{oss} | V _{DS} = 15V | - | 330 | - | pF |
| Reverse transfer capacitance | C _{rss} | f = 1MHz | 1 | 270 | 1 | |
| Turn - on delay time | $t_{d(on)}^{*4}$ | V _{DD} ≃ 15V,V _{GS} = 10V | 1 | 25 | 1 | |
| Rise time | t _r *4 | I _D = 7A | - | 30 | - | no |
| Turn - off delay time | t _{d(off)} *4 | R _L ≃ 2.1Ω | - | 85 | - | ns |
| Fall time | t _f *4 | $R_G = 10\Omega$ | - | 40 | - | |

● Gate charge characteristics (T_a = 25°C) < Tr1 and Tr2>

| | 0 1 1 | O III | Values | | | 11.7 |
|----------------------|--------------------|---|--------|------|------|------|
| Parameter | Symbol | Conditions | Min. | Тур. | Max. | Unit |
| Total gate charge | Q _g *4 | | - | 24 | - | |
| Gate - Source charge | Q _{gs} *4 | V _{DD} ≃ 15V, I _D = 14A V _{GS} = 4.5V | - | 7.5 | - | nC |
| Gate - Drain charge | Q _{gd} *4 | | - | 9.0 | - | |

● Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

<Tr1 and Tr2>

| Parameter | Symbol Conditions | | Values | | | - Unit | |
|----------------------------|--------------------|-----------------------------|--------|------|------|--------|--|
| raianietei | Symbol | ool Conditions | | Тур. | Max. | Offic | |
| Continuous forward current | I _S *1 | T - 25°C | - | - | 2.5 | Α | |
| Pulse forward current | I _{SP} *2 | T _a = 25℃ | - | - | 28 | Α | |
| Forward voltage | V _{SD} *4 | $V_{GS} = 0V, I_{S} = 2.5A$ | - | - | 1.2 | V | |

• Electrical characteristics curves < Tr1 and Tr2>

Fig.1 Power Dissipation Derating Curve

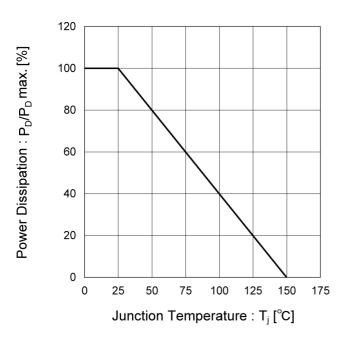
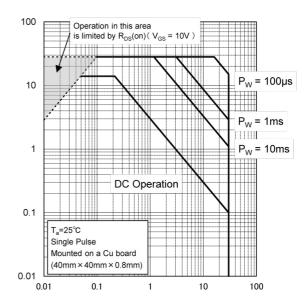


Fig.2 Maximum Safe Operating Area



Drain Current : I_D [A]

Drain - Source Voltage : V_{DS} [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

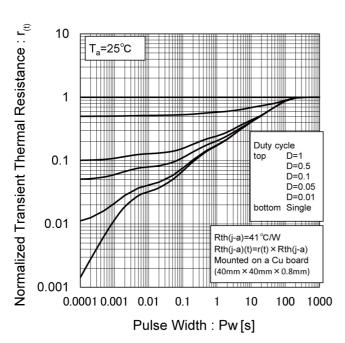
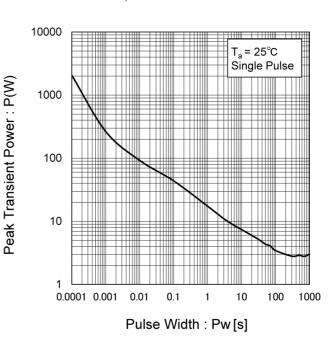
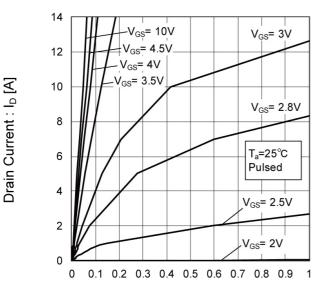


Fig.4 Single Pulse Maximum Power Dissipation



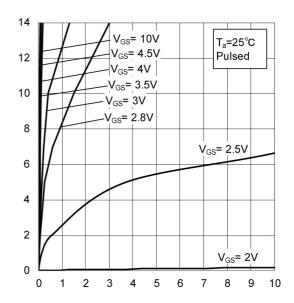
Drain Current : I_D [A]

Fig.5 Typical Output Characteristics(I)



Drain - Source Voltage : V_{DS} [V]

Fig.6 Typical Output Characteristics(II)



Drain - Source Voltage : V_{DS} [V]

Fig.7 Breakdown Voltage vs.
Junction Temperature

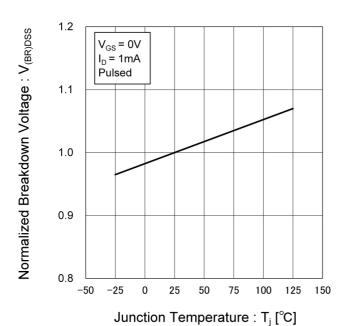


Fig.8 Typical Transfer Characteristics

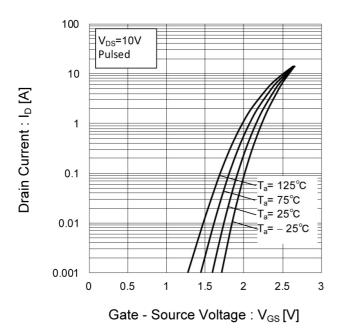


Fig.9 Gate Threshold Voltage vs.
Junction Temperature

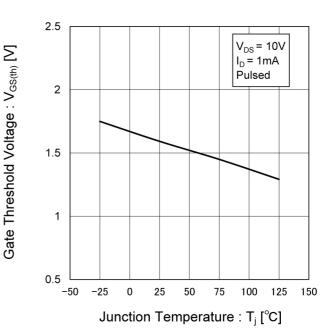
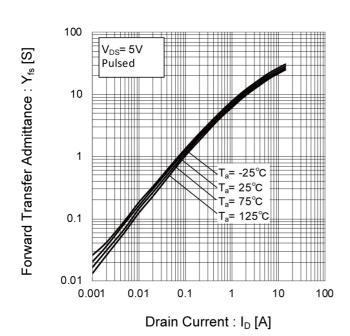


Fig.10 Forward Transfer Admittance vs.
Drain Current



6/11

Fig.11 Drain Current Derating Curve

120 100 Drain Current Dissipation 80 : I_D/I_Dmax. [%] 60 40 20 0 -25 0 25 50 75 100 125 150 Junction Temperature : T_j [°C]

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

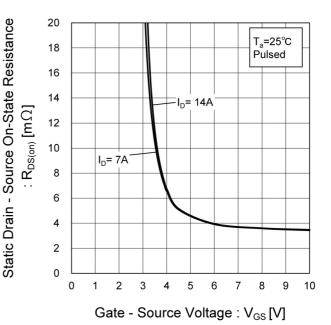
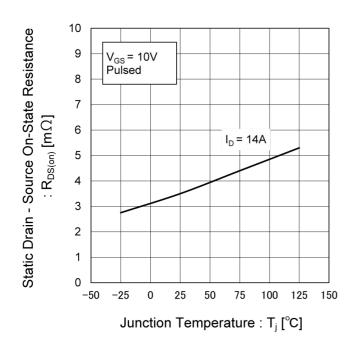


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature



0.1

0.1

• Electrical characteristics curves < It is the same characteristics for the Tr1 and Tr2>

Fig.14 Static Drain - Source On - State Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (I) Resistance vs. Drain Current (II) 100 Static Drain - Source On-State Resistance 100 Static Drain - Source On-State Resistance T_a=25°C V_{GS}= 10V 125°C Pulsed Pulsed = 75°C T_a= 25°C - 25°C 10 10 $R_{\text{DS(on)}}\left[\text{m}\Omega\right]$ $R_{DS(on)}$ [m Ω] 1

100

0.1

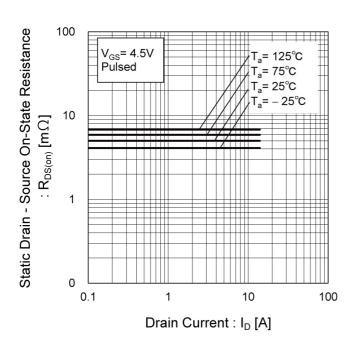
0.1

Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)

Drain Current: ID [A]

10

1



10

Drain Current: I_D [A]

100

Fig.17 Typical Capacitances vs.

Drain - Source Voltage

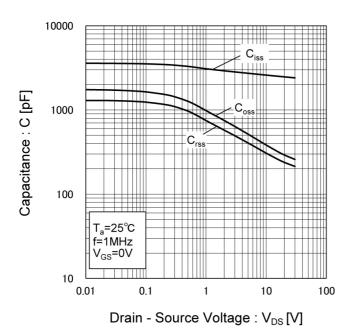


Fig.18 Switching Characteristics

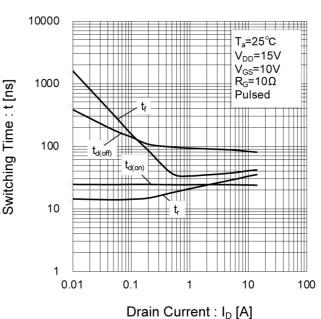


Fig.19 Typical Gate Charge

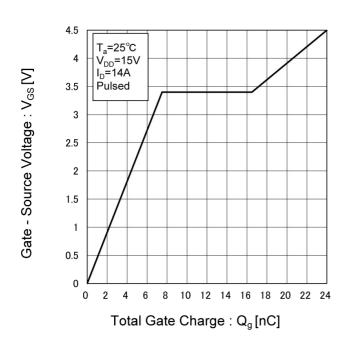
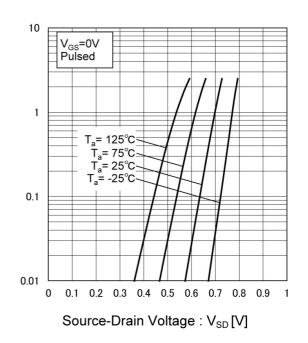


Fig.20 Source Current vs. Source Drain Voltage



Source Current : Is [A]

Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

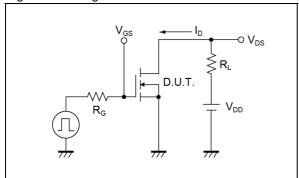


Fig.2-1 Gate Charge Measurement Circuit

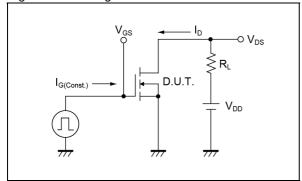


Fig.1-2 Switching Waveforms

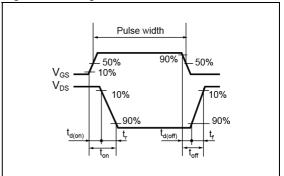
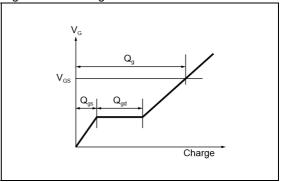
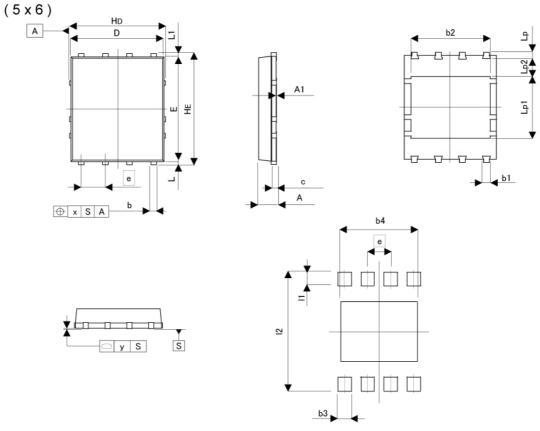


Fig.2-2 Gate Charge Waveform



Dimensions

HSOP8 (Drain common)



Pattern of terminal position areas [Not a pattern of soldering pads]

| | MILIMETERS INCHES | | | | | |
|-----|-------------------|------|-------|-------|--|--|
| DIM | | | | | | |
| | MIN | MAX | MIN | MAX | | |
| Α | 0.90 | 1.10 | 0.035 | 0.043 | | |
| A1 | 0.00 | 0.05 | 0.000 | 0.002 | | |
| b | 0.24 | 0.42 | 0.009 | 0.017 | | |
| b1 | 0.22 | 0.52 | 0.009 | 0.020 | | |
| b2 | 4.00 | 4.40 | 0.157 | 0.173 | | |
| С | 0.20 | 0.30 | 0.008 | 0.012 | | |
| D | 4.80 | 5.00 | 0.189 | 0.197 | | |
| E | 5.60 | 5.80 | 0.220 | 0.228 | | |
| е | 1. | 27 | 0.0 |)50 | | |
| HD | 4.90 | 5.10 | 0.193 | 0.201 | | |
| HE | 5.90 | 6.10 | 0.232 | 0.240 | | |
| L | 0.07 | 0.25 | 0.003 | 0.010 | | |
| L1 | 0.07 | 0.25 | 0.003 | 0.010 | | |
| Lp | 0.27 | 0.47 | 0.011 | 0.019 | | |
| Lp1 | 3.12 | 3.52 | 0.123 | 0.139 | | |
| Lp2 | 0. | 97 | 0.0 |)38 | | |
| х | - | 0.10 | - | 0.004 | | |
| у | - | 0.10 | - | 0.004 | | |

| DIM | MILIMETERS | | INC | HES |
|-------|------------|------|------|-------|
| Dilvi | MIN | MAX | MIN | MAX |
| b3 | - | 0.62 | 18.3 | 0.024 |
| b4 | - | 4.40 | - | 0.173 |
| 11 | - | 0.57 | | 0.022 |
| 12 | - | 6.10 | 1 | 0.240 |

Dimension in mm/inches



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|---------|----------|------------|----------|
| CLASSⅢ | CLASSⅢ | CLASS II b | CL ACCTI |
| CLASSIV | CLASSIII | CLASSⅢ | CLASSIII |

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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
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